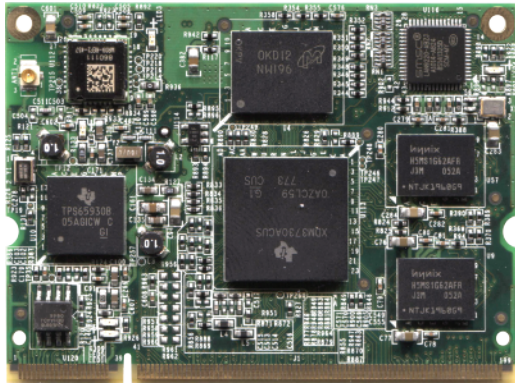


TDM-3730

System on Module



Key Features

TI Sitara DM3730 application processor with ARM Cortex-A8 CPU, and POWERVR SGX 530 for 2D and 3D graphics acceleration.

200 pin SO-DIMM connector carrying LAN, USB, UART, SPI, I²C, LCD Camera signals making the TDM-3730 ideal for industrial and multimedia usage.

Board Support Packages (BSP) available to create your own applications ranging from Windows CE to Linux and Android.

Specifications

System

CPU	TI Sitara 3730 @ 1GHz
DSP core	TMS320C64x+™ @ 800MHz
Memory	512 MB Low power mobile DDR optional configurations upto 1GB
Storage	512 MB NAND Flash
Wireless LAN	802.11b/g
Supported OS	Linux 2.6.x, WinCE 6 and Android

Interfaces

Connectors	200 pin SO-DIMM with SPI, UART, USB host, USB OTG/ client, I ² C, PWM lines, 1-wire, MMC lines, A/D lines, camera, audio in/out, mic keypad, S-Video, Display, LAN
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Graphic Capabilities

Chipset	POWERVR SGX 530 20Mpolys/s, up to 720p resolution
API support	OpenGL 2.0, OpenGLes 1.1, OpenVG 1.0

Power

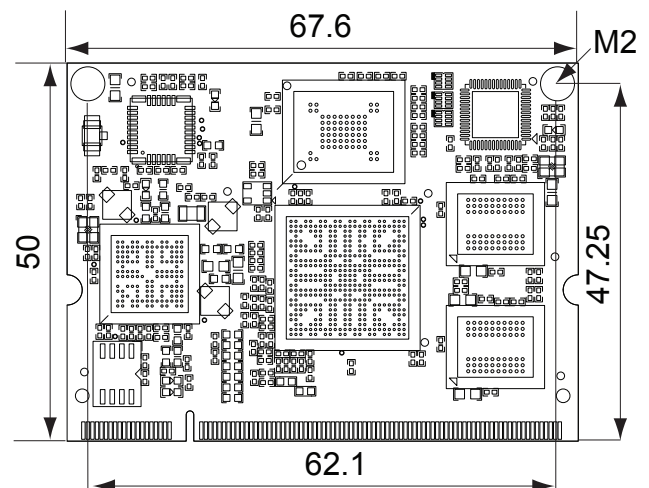
Power consumption	<2.0 Watt with Wireless enabled
Standby	<50 mWatt
Power requirements	5V

Environmental and Mechanical

Temperature	Commercial: 0° to 70° C Extended: -20° to 70° C Industrial: -40° to 85° C
Humidity	10-90%
Dimensions	67.6x 50x 3.4 mm (2 5/8x 2x 1/4 inch)
MTBF	>100,000 hours
Weight	12 grams
Shock	50G / 25ms
Vibration	20G / 0-600 Hz

Dimensions

units in mm



Order Information

TDM-3730	DM3730 System on Module
TDM-3730W	DM3730 System on Module with Wireless LAN 802.11 b/g

Other configurations and storage capacities on project basis and subject to minimum order quantities

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